



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

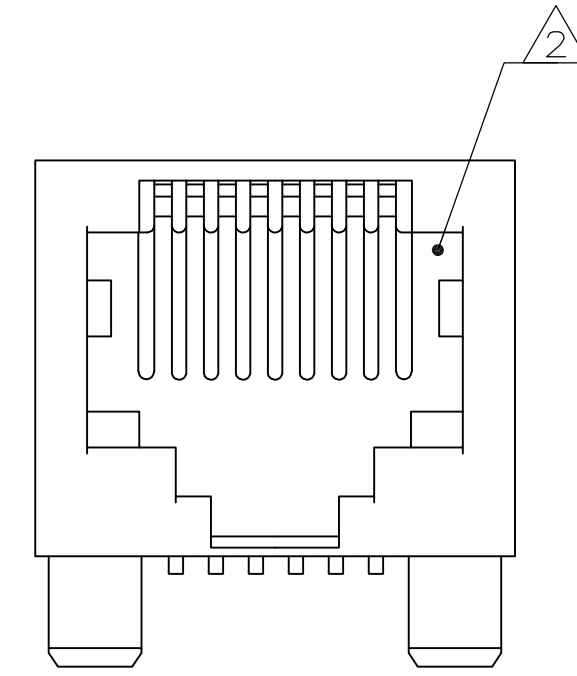
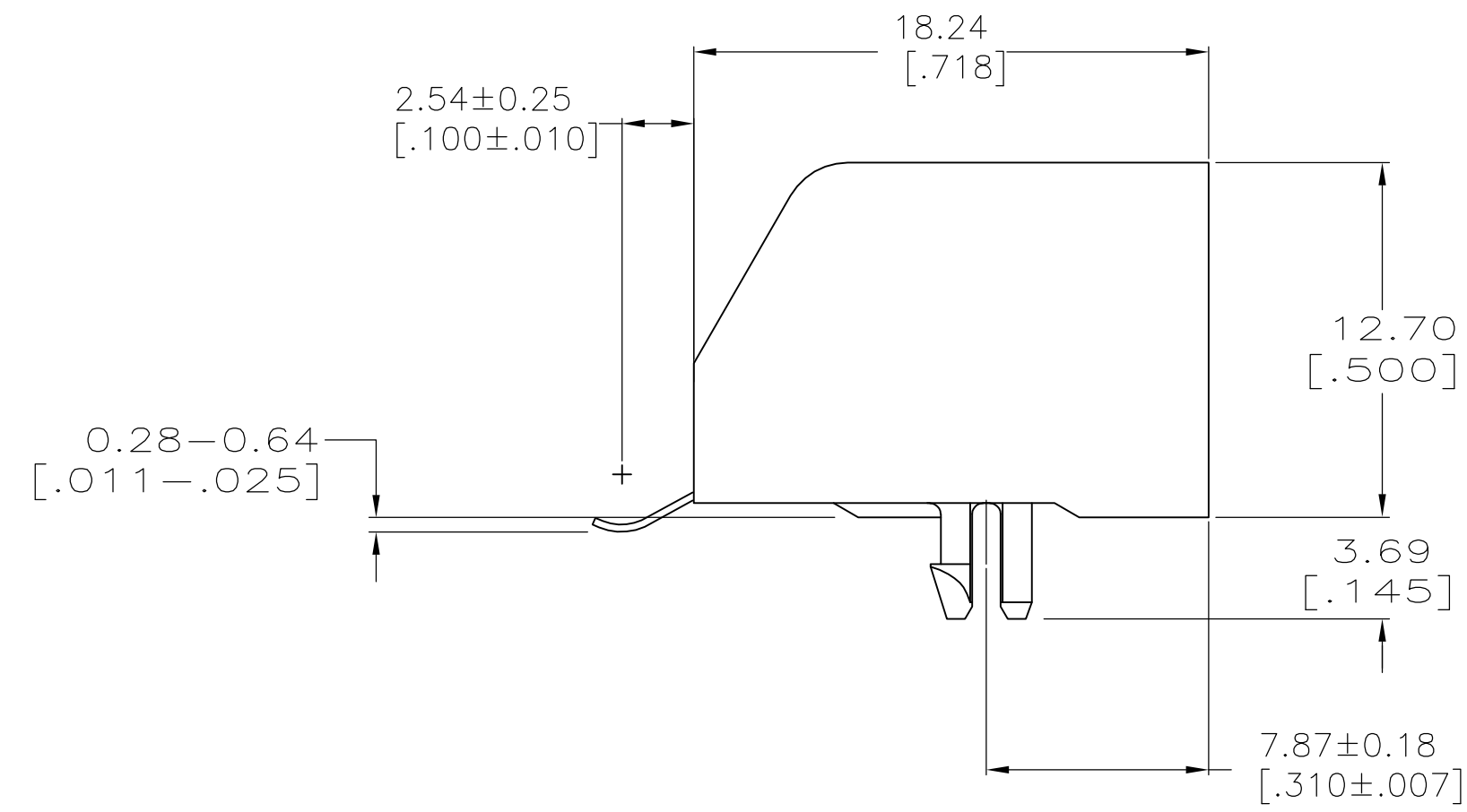
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LOC	DIST	REVISIONS					
AA	00	P	LTR	DESCRIPTION	DATE	DWN	APPD
		C1		REVISED PER ECO-11-005033	23MAR11	RK	HMR



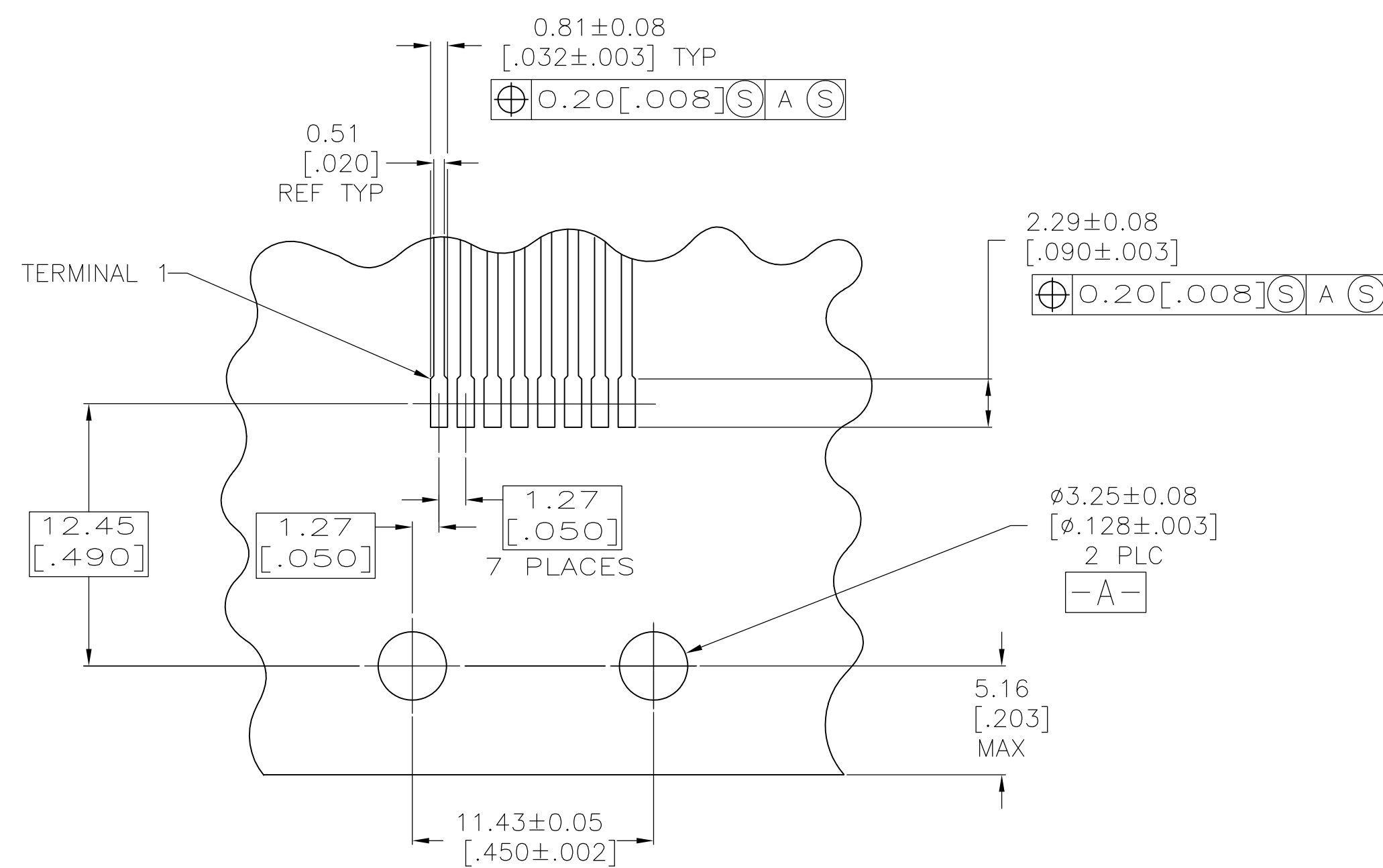
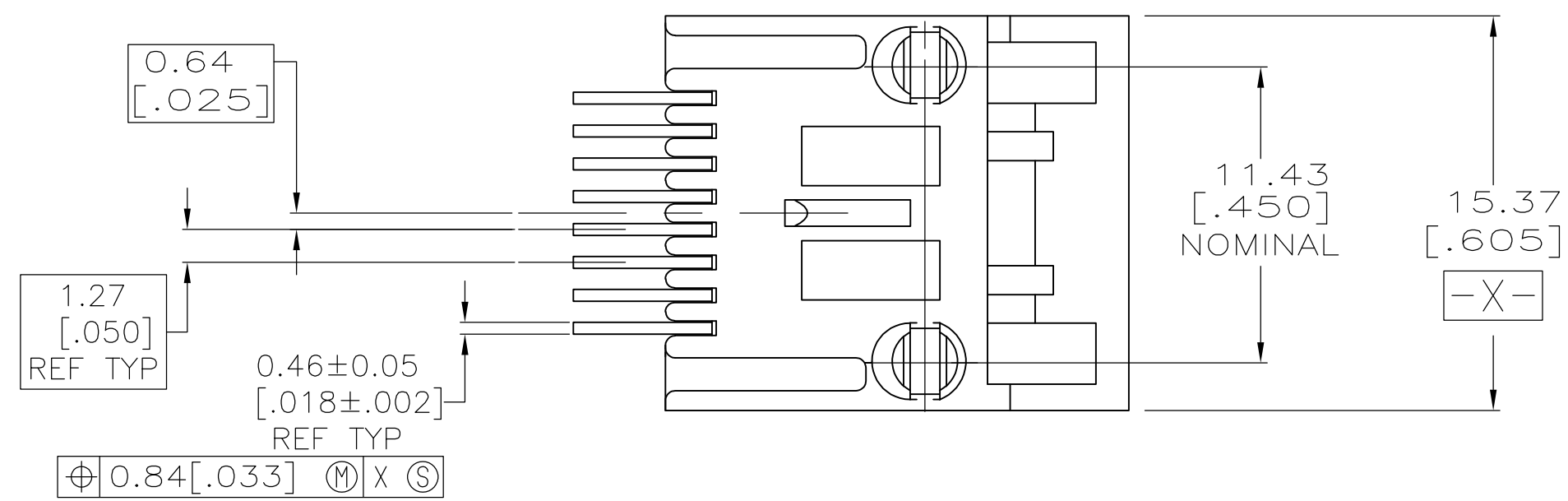
- MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK.
TERMINAL - 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27µm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] MINIMUM THICK NICKEL UNDERPLATE.

△ CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.

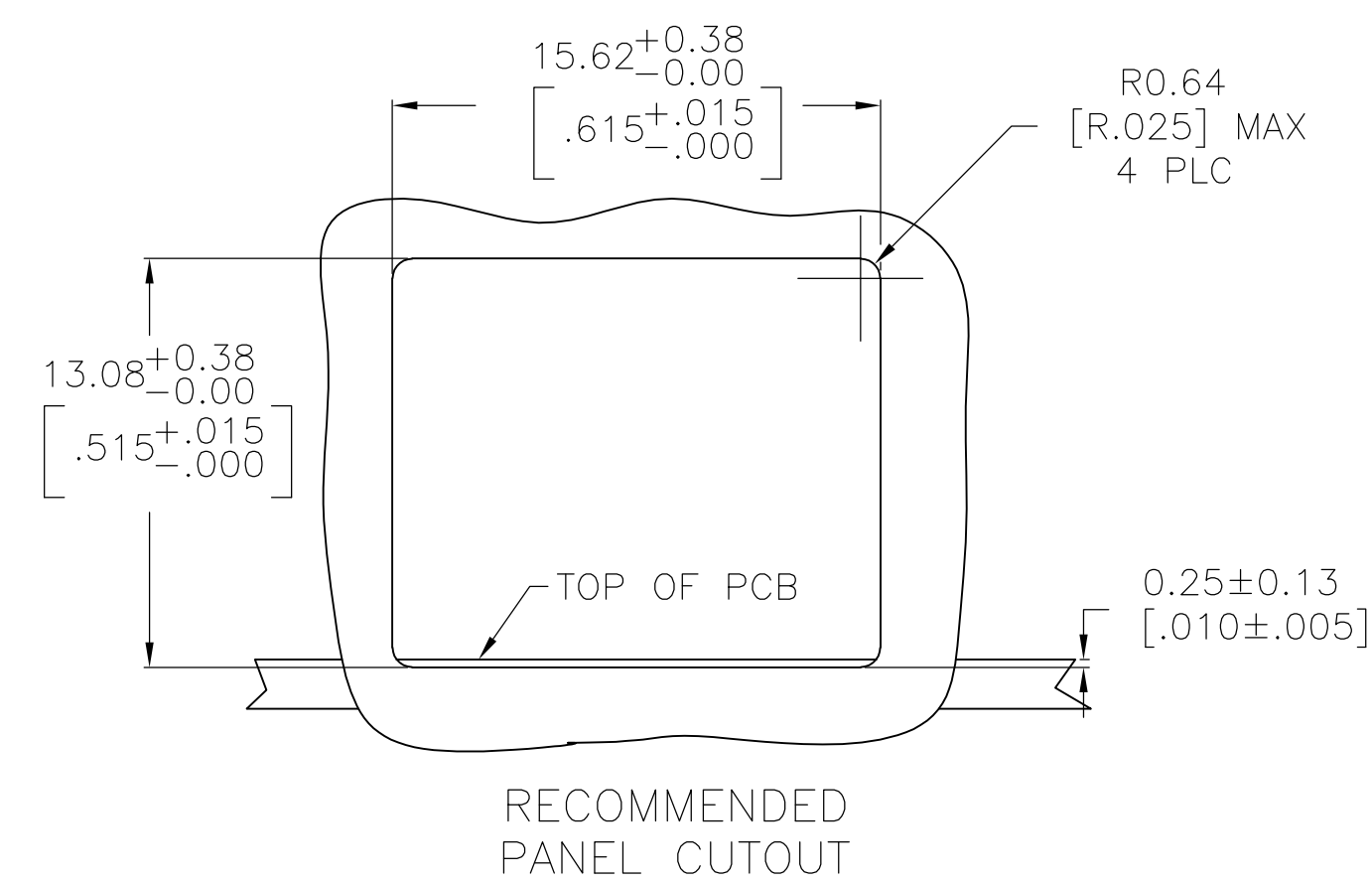
- ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.

△ ASSEMBLIES ARE PACKAGED 36 IN A TUBE.

△ ASSEMBLIES ARE PACKAGED IN TRAYS.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE



RECOMMENDED PANEL CUTOUT

△ 5	5555764-3
△ 6	5555764-1
PACKAGED	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN G. ATTADIA - DOCKS 09JUN2005	CHK J. WESTMAN 09JUN2005	APVD S. FLICKINGER 09JUN2005	NAME	TE Connectivity	
DIMENSIONS: mm(INCHES)		TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC		MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT	
0 PLC ± -		1 PLC ± -		2 PLC ± -		3 PLC ± -	
4 PLC ± -		ANGLES ± -		108-1163		SIZE CAGE CODE DRAWING NO	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		114-6040		RESTRICTED TO	
CUSTOMER DRAWING		SCALE 4:1		SHEET 1 OF 1		REV C1	